



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	17-02-2023
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM8AF62A9TCX	JT5W*79AX25T	A	959	17-02-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	350.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10	64	L bend	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	JTSW*79AX25T				6000000.0	1000003.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	6.684	mg	supplier	die	Silicon (Si)	7440-21-3		6.478	mg	969180	18509
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	2693	51
				supplier	metallization	Copper (Cu)	7440-50-8		0.060	mg	8977	171
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.007	mg	1047	20
				supplier	metallization	Titanium (Ti)	7440-32-6		0.009	mg	1346	26
				supplier	Passivation	Silicon Nitride	12033-89-5		0.016	mg	2394	46
				supplier	Passivation	Silicon Oxide	7631-86-9		0.096	mg	14363	274
Leadframe	M-011 Other inorganic materials	100.125	mg	Supplier	alloy	Copper (Cu)	7440-50-8		96.320	mg	962000	275200
				Supplier	alloy	Nickel (Ni)	7440-02-0		3.004	mg	30000	8582
				Supplier	alloy	Silicium (Si)	7440-21-3		0.651	mg	6500	1859
				Supplier	alloy	Magnesium (Mg)	7439-95-4		0.150	mg	1500	429
Glue (EN4900GC-SD)	M-011 Other inorganic materials	3.625	mg	Supplier	glue or soft solder	Silver (Ag)	7440-22-4		2.936	mg	810000	8388
				Supplier	glue or soft solder	Ethylene glycol dicyclopentyl ether acrylate	65983-31-5		0.236	mg	65000	673
				Supplier	glue or soft solder	Copolymer	64401-02-1		0.217	mg	60000	621
				supplier	glue or soft solder	Epoxy resin	65983-31-5		0.145	mg	40000	414
				supplier	glue or soft solder	Butadiene copolymer	68891-50-9		0.072	mg	20000	207
supplier	glue or soft solder	Cyclohexylidenebis(tert-butyl)peroxide	3006-86-8		0.018	mg	5000	52				
Wire (Au 2N)	M-011 Other inorganic materials	0.823	mg	Supplier	Bonding wire	Gold (Au)	7440-57-5		0.823	mg	1000000	2350
Encapsulation (EME-G700LS)	M-011 Other inorganic materials	232.549	mg	Supplier	Moulding Compound	Solid Epoxy Resin	Proprietary		17.812	mg	76596	50892
				Supplier	Moulding Compound	Phenol Resin	Proprietary		8.906	mg	38298	25446
				Supplier	Moulding Compound	Silica, vitreous	60676-86-0		203.827	mg	876489	582363
				Supplier	Moulding Compound	Carbon-black	1333-86-4		1.113	mg	4787	3181
Supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.891	mg	3830	2545				
Finishing (Pure_Tin)	M-011 Other inorganic materials	6.196	mg	Supplier	connections coating	Tin (Sn)	7440-31-5		6.196	mg	1000000	17703